

Version with Markings to Show Changes Made

Claim 1 is amended as follows.

1. (Amended) A semiconductor die package, comprising:

conductive outer leads having first ends extending outside an encapsulant body of the package and second ends extending [toward the] into an interior of the encapsulant body of the package;

conductive inner leads within the encapsulant body and having first ends extending to and electrically accessible through a first surface of the encapsulant body of the package; and

a first die within the encapsulant body and electrically connected to the inner and outer leads.

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